

MOSFET – Power, N-Channel, SUPERFET[®] III, Easy Drive

650 V, 24 A, 125 mΩ

FCPF125N65S3

Description

SUPERFET III MOSFET is **onsemi**'s brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provides superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET Easy drive series helps manage EMI issues and allows for easier design implementation.

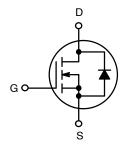
Features

- 700 V @ T_J = 150°C
- Typ. $R_{DS(on)} = 105 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q_g = 44 nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 405 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

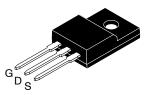
Applications

- Computing / Display Power Supplies
- Telecom / Server Power Supplies
- Industrial Power Supplies
- Lighting / Charger / Adapter

V _{DSS}	V _{DSS} R _{DS(ON)} MAX	
650 V	125 mΩ @ 10 V	24 A

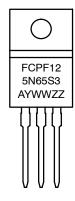


POWER MOSFET



TO-220 Fullpack CASE 221AT

MARKING DIAGRAM



FCPF125N65S3 = Specific Device Code
A = Assembly Location
YWW = Date Code (Year & Week)

ZZ = Assembly Lot

ORDERING INFORMATION

Device	Package	Shipping		
FCPF125N65S3	TO-220 Fullpack	1000 Units / Tube		

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$, Unless otherwise noted)

Symbol	Parameter	Value	Unit		
V_{DSS}	Drain to Source Voltage		650	V	
V _{GSS}	Gate to Source Voltage	- DC	±30	V	
		- AC (f > 1 Hz)	±30		
I _D	Drain Current	– Continuous (T _C = 25°C)	24*	Α	
		– Continuous (T _C = 100°C)	15*		
I _{DM}	Drain Current	- Pulsed (Note 1)	60*	Α	
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		115	mJ	
I _{AS}	Avalanche Current (Note 2)		3.7	Α	
E _{AR}	Repetitive Avalanche Energy (Note 1)		0.38	mJ	
dv/dt	MOSFET dv/dt		100	V/ns	
	Peak Diode Recovery dv/dt (Note 3)		20	İ	
P_{D}	Power Dissipation	(T _C = 25°C)	38	W	
		- Derate Above 25°C	0.31	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds		300	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
*Drain current limited by maximum junction temperature.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.	3.24	°C/W
$R_{ heta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	

Repetitive rating: pulse–width limited by maximum junction temperature.
 I_{AS} = 3.7 A, R_G = 25 Ω, starting T_J = 25°C.
 I_{SD} ≤ 12 A, di/dt ≤ 200 A/μs, V_{DD} ≤ 400 V, starting T_J = 25°C.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
OFF CHARACT	ERISTICS				•	
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$	650			V
		V _{GS} = 0 V, I _D = 1 mA, T _J = 150°C	700			V
$\Delta BV_{DSS} / \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I _D = 1 mA, Referenced to 25°C		0.65		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V			1	μΑ
		V _{DS} = 520 V, T _C = 125°C		1.35		1
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
ON CHARACTE	RISTICS					
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 0.54 \text{ mA}$	2.5		4.5	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 12 A		105	125	mΩ
9FS	Forward Transconductance	V _{DS} = 20 V, I _D = 12 A		16		S
DYNAMIC CHAI	RACTERISTICS				-	
C _{iss}	Input Capacitance	V _{DS} = 400 V, V _{GS} = 0 V, f = 1 MHz		1790		pF
C _{oss}	Output Capacitance			40		pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		405		pF
C _{oss(er.)}	Energy Related Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		60		pF
Q _{g(tot)}	Total Gate Charge at 10 V	V _{DS} = 400 V, I _D = 12 A, V _{GS} = 10 V		44		nC
Q_{gs}	Gate to Source Gate Charge	(Note 4)		12		nC
Q_{gd}	Gate to Drain "Miller" Charge			19		nC
ESR	Equivalent Series Resistance	f = 1 MHz		4		Ω
SWITCHING CH	IARACTERISTICS					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 400 \text{ V}, I_D = 12 \text{ A}, V_{GS} = 10 \text{ V},$		22		ns
t _r	Turn-On Rise Time	$R_g = 4.7 \Omega$ (Note 4)		25		ns
t _{d(off)}	Turn-Off Delay Time			60		ns
t _f	Turn-Off Fall Time			15		ns
SOURCE-DRAII	N DIODE CHARACTERISTICS					
I _S	Maximum Continuous Source to Drain Diode Forward Current				24	Α
I _{SM}	Maximum Pulsed Source to Drain Diode Forward Current				60	Α
V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 12 A			1.2	V
t _{rr}	Reverse Recovery Time	V _{DD} = 400 V, I _{SD} = 12 A,		362		ns
Q _{rr}	Reverse Recovery Charge	dl _F /dt = 100 A/μs		6.36		μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

TYPICAL PERFORMANCE CHARACTERISTICS

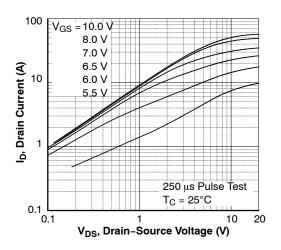


Figure 1. On-Region Characteristics

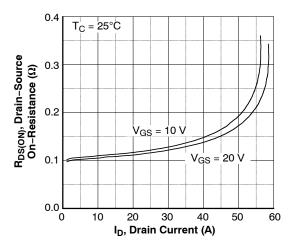


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

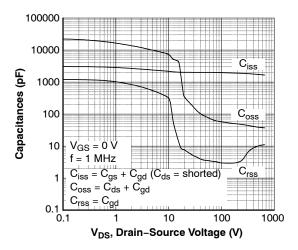


Figure 5. Capacitance Characteristics

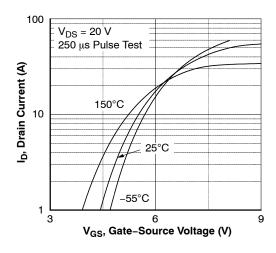


Figure 2. Transfer Characteristics

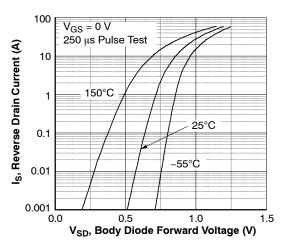


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

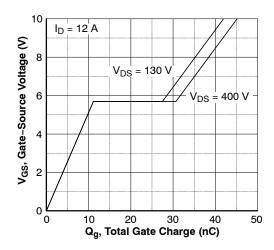


Figure 6. Gate Charge Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS (CONTINUED)

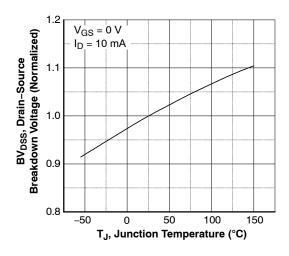


Figure 7. Breakdown Voltage Variation vs. Temperature

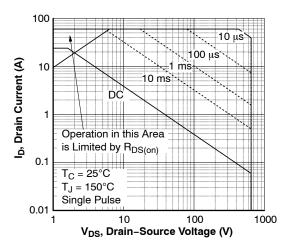


Figure 9. Maximum Safe Operating Area

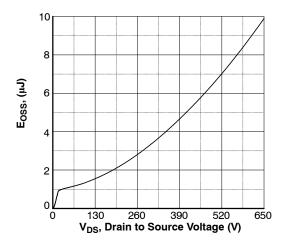


Figure 11. $E_{\mbox{OSS}}$ vs. Drain to Source Voltage

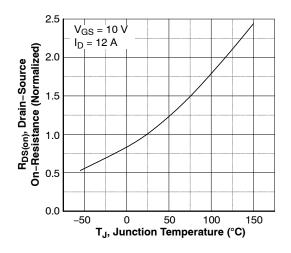


Figure 8. On–Resistance Variation vs. Temperature

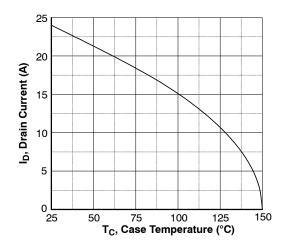


Figure 10. Maximum Drain Current vs. Case Temperature

TYPICAL PERFORMANCE CHARACTERISTICS (CONTINUED)

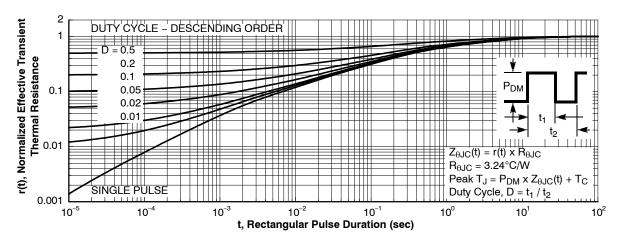


Figure 12. Transient Thermal Response Curve

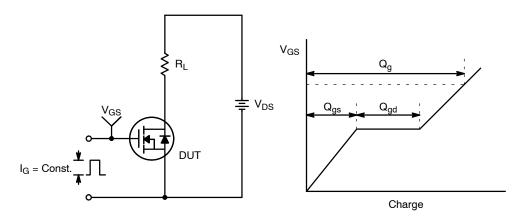


Figure 13. Gate Charge Test Circuit & Waveform

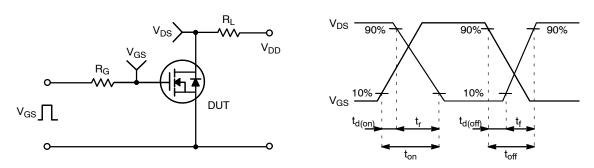


Figure 14. Resistive Switching Test Circuit & Waveforms

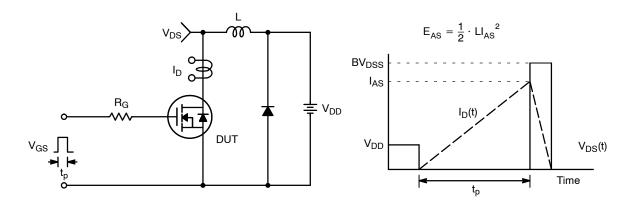


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

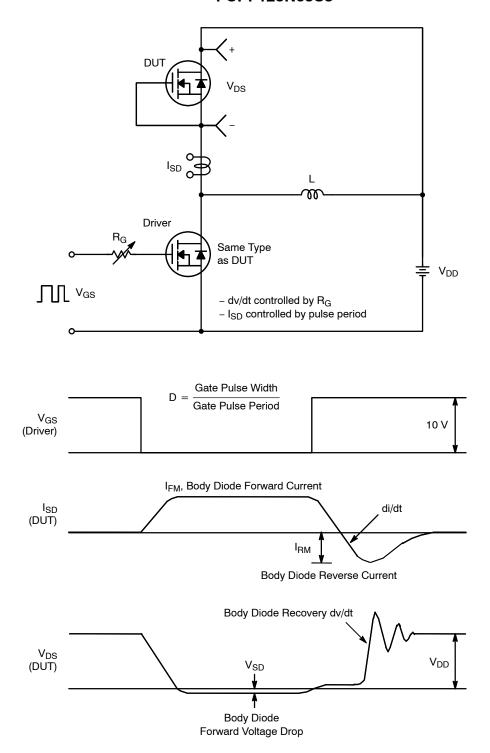
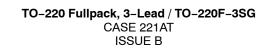
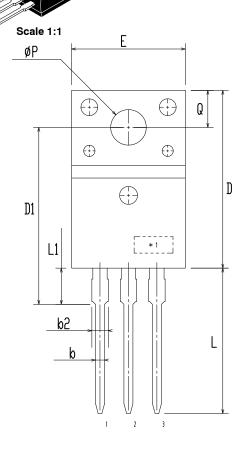


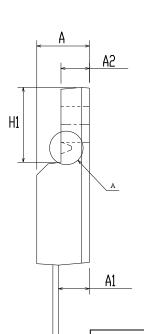
Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

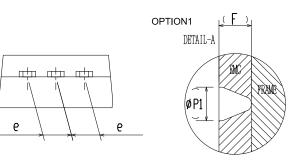
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DATE 19 JAN 2021







DIM	MILLIMITERS			
ויונע	MIN	NDM	MAX	
Α	4.50	4.70	4.90	
A1	2.56	2.76	2.96	
A2	2.34	2.54	2.74	
b	0.70	0.80	0.90	
b2	~	2	1.47	
С	0.45	0.50	0.60	
D	15.67	15.87	16.07	
D1	15.60	15.80	16.00	
E	9.96	10.16	10.36	
е	2.34	2.54	2.74	
F	~	0.84	2	
H1	6.48	6.68	6.88	
L	12.78	12.98	13.18	
L1	3.03	3.23	3.43	
ØΡ	2.98	3.18	3.38	
Ø P1	~	1.00	~	
Q	3.20	3.30	3.40	

MILLIMITEDS

NOTES:

- A. DIMENSION AND TOLERANCE AS ASME Y14.5-2009
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUCSIONS.

C

C. OPTION 1 - WITH SUPPORT PIN HOLE OPTION 2 - NO SUPPORT PIN HOLE

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